

## 100V Single N-Channel Enhancement-Mode MOSFET

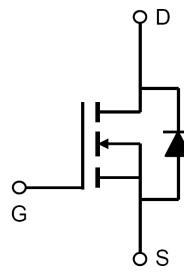
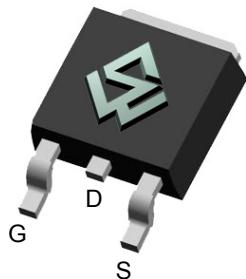
### General Description

- Low  $R_{Dson}$ .
- Fully characterized Avalanche voltage and current.
- EAS 100% Test

### Product Summary

- |                                  |        |
|----------------------------------|--------|
| • $BV_{DSS}$                     | 100V   |
| • $R_{DS(on)}$ @ $V_{GS} = 10V$  | < 45mΩ |
| • $R_{DS(on)}$ @ $V_{GS} = 4.5V$ | < 75mΩ |

TO-252 D-PAK



### Absolute Maximum Ratings ( $T_A = 25^\circ C$ unless otherwise noted)

Parameter	Symbol	Maximum	Units
Drain-Source Voltage	$V_{DS}$	100	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Drain Current ( $T_A=25^\circ C$ )	$I_D$	30	A
Drain Current ( $T_C=100^\circ C$ )		15	A
Pulsed Drain Current <sup>a</sup>	$I_{DM}$	80	A
Single Pulse Avalanche energy <sup>b</sup>	$E_{AS}$	40	mJ
Power Dissipation	$P_D$	43	W
Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 ~ +150	°C

### Thermal Characteristics

Parameter	Symbol	Maximum	Units
Thermal Resistance, Junction-to-Case <sup>c</sup>	$R_{\theta JC}$	3.0	°C/W
Thermal Resistance Junction-Ambient	$R_{\theta JA}$	50	°C/W

<b>Electrical Characteristics (<math>T_A = 25^\circ\text{C}</math> unless otherwise noted)</b>						
<b>Symbol</b>	<b>Parameter</b>	<b>Conditions</b>	<b>Min</b>	<b>Typ</b>	<b>Max</b>	<b>Units</b>
<b>Off Characteristics</b>						
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}} = 0\text{V}$ , $I_{\text{D}} = 250\mu\text{A}$	100			V
$I_{\text{DSS}}$	Zero Gate Voltage Drain Current	$V_{\text{DS}} = 100\text{V}$ , $V_{\text{GS}} = 0\text{V}$			1	$\mu\text{A}$
$I_{\text{GSS}}$	Gate-Body Leakage Current	$V_{\text{GS}} = \pm 20\text{V}$ , $V_{\text{DS}} = 0\text{V}$			$\pm 100$	nA
<b>On Characteristics</b>						
$V_{\text{GS}(\text{th})}$	Gate Threshold Voltage	$V_{\text{DS}} = V_{\text{GS}}$ , $I_{\text{D}} = 250\mu\text{A}$	1	-	2.5	V
$R_{\text{DS}(\text{ON})}$	Drain-Source On-State Resistance	$V_{\text{GS}} = 10\text{V}$ , $I_{\text{D}} = 5\text{A}$		32	45	$\text{m}\Omega$
		$V_{\text{GS}} = 4.5\text{V}$ , $I_{\text{D}} = 3\text{A}$		38	75	$\text{m}\Omega$
<b>Drain-Source Diode Characteristics</b>						
$V_{\text{SD}}$	Diode Forward Voltage	$V_{\text{GS}} = 0\text{V}$ , $I_{\text{S}} = 12.5\text{A}$		0.85	1.3	V
$I_{\text{S}}$	Maximum Body-Diode Continuous Current				30	A
<b>Dynamic Characteristics</b>						
$C_{\text{iss}}$	Input Capacitance	$V_{\text{DS}} = 50\text{V}$ , $V_{\text{GS}} = 0\text{V}$ $f = 1.0\text{MHz}$		2420		pF
$C_{\text{oss}}$	Output Capacitance			120		pF
$C_{\text{rss}}$	Reverse Transfer Capacitance			80		pF
<b>Switching Characteristics</b>						
$Q_{\text{g}}$	Total Gate Charge	$V_{\text{DS}} = 50\text{V}$ , $I_{\text{D}} = 10\text{A}$ $V_{\text{GS}} = 10\text{V}$		55		nC
$Q_{\text{gs}}$	Gate-Source Charge			9		nC
$Q_{\text{gd}}$	Gate-Drain Charge			8		nC
$t_{\text{D}(\text{ON})}$	Turn-On Delay Time	$V_{\text{DD}} = 50\text{V}$ , $I_{\text{D}} = 1\text{A}$ $V_{\text{GS}} = 10\text{V}$ $R_{\text{GEN}} = 6.8\text{ ohm}$		12		ns
$t_{\text{r}}$	Turn-On Rise Time			42		ns
$t_{\text{D}(\text{OFF})}$	Turn-Off Delay Time			58		ns
$t_{\text{f}}$	Turn-Off Fall Time			45		ns

- a. Repetitive rating, Pulse width limited by junction temperature  $T_{\text{J}(\text{MAX})}=150^\circ\text{C}$ . Ratings are based on low frequency and duty cycles to keep initial  $T_{\text{J}}=25^\circ\text{C}$
- b. EAS Condition:  $T_{\text{J}}=25^\circ\text{C}$ ,  $V_{\text{DD}}=15\text{V}$ ,  $V_{\text{G}}=10\text{V}$ ,  $L=10\text{mH}$ ,  $R_{\text{g}}=25\Omega$
- c. The value of  $R_{\theta_{\text{JC}}}$  is measured with the device mounted on 1in<sup>2</sup> FR-4 board with 2oz. Copper, in a still air environment with  $T_A = 25^\circ\text{C}$ . The value in any given application depends on the user's specific board design.

## Typical Characteristics

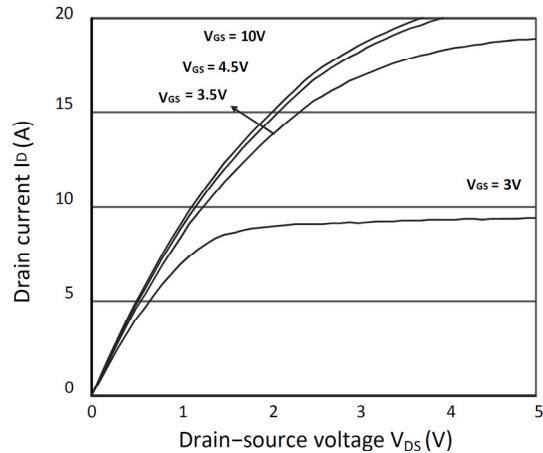


Figure 1. Output Characteristics

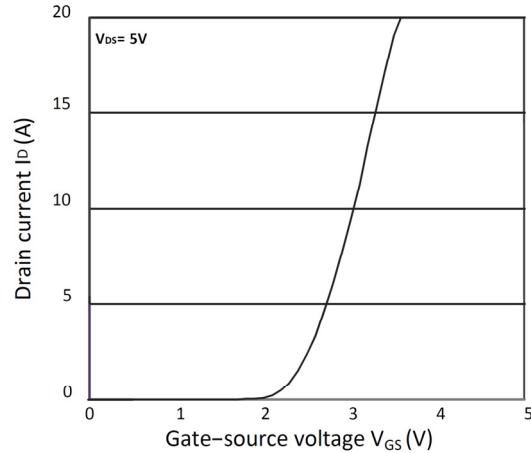


Figure 2. Transfer Characteristics

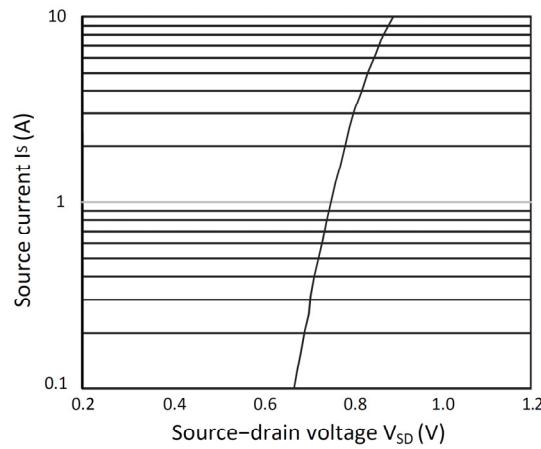


Figure 3. Forward Characteristics of Reverse

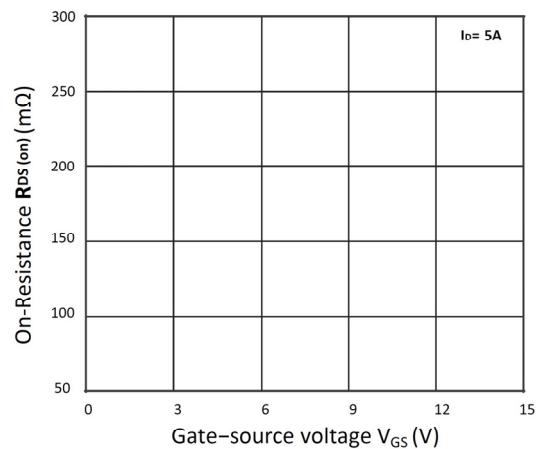


Figure 4.  $R_{DS(ON)}$  vs.  $V_{GS}$

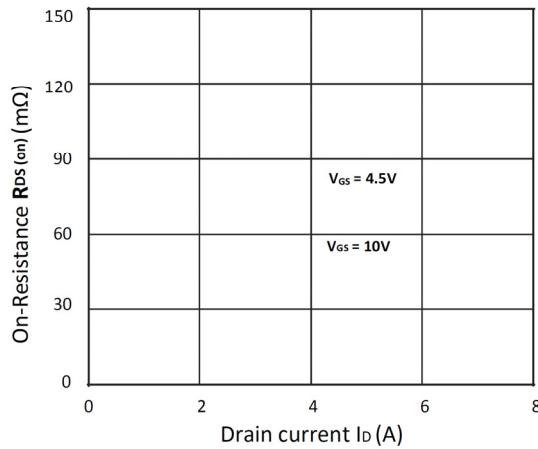


Figure 5.  $R_{DS(ON)}$  vs.  $I_D$

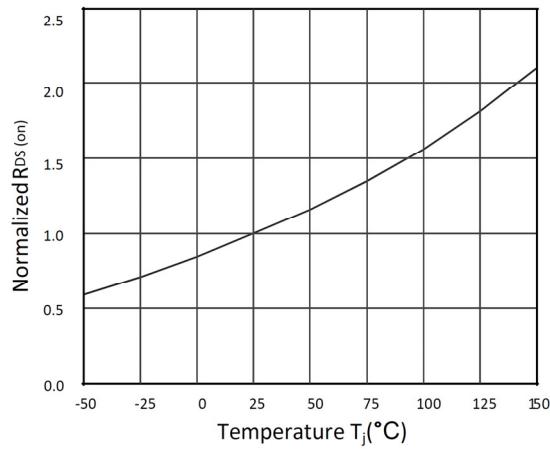


Figure 6. Normalized  $R_{DS(on)}$  vs. Temperature

## Typical Characteristics

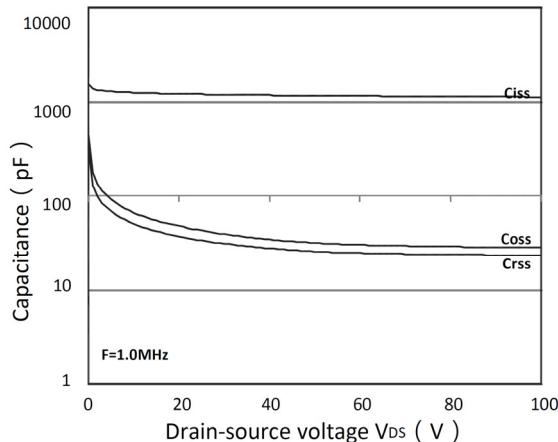


Figure 7. Capacitance Characteristics

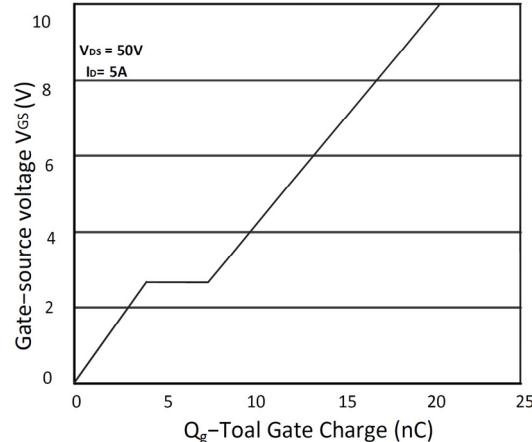


Figure 8. Gate Charge Characteristics

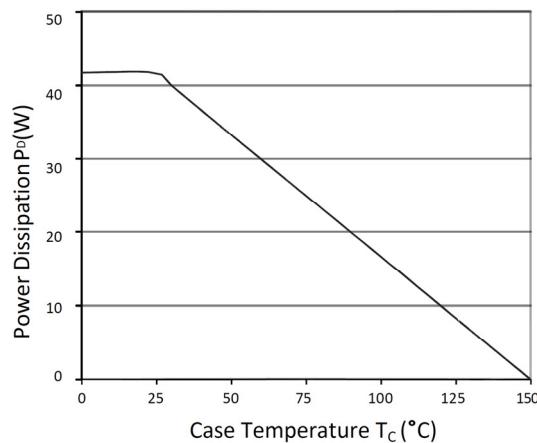


Figure 9. Power Dissipation

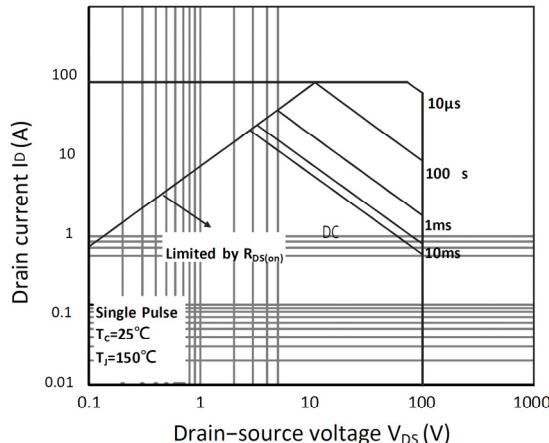


Figure 10. Safe Operating Area

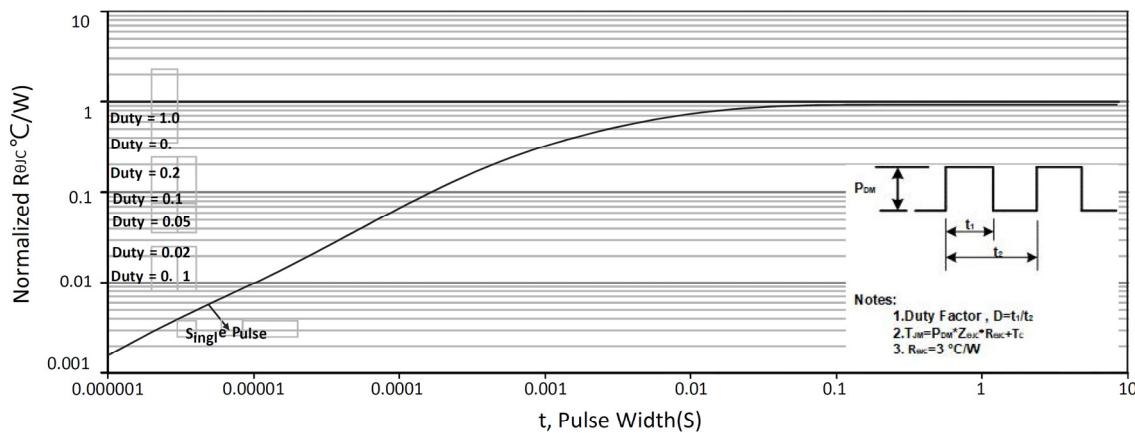
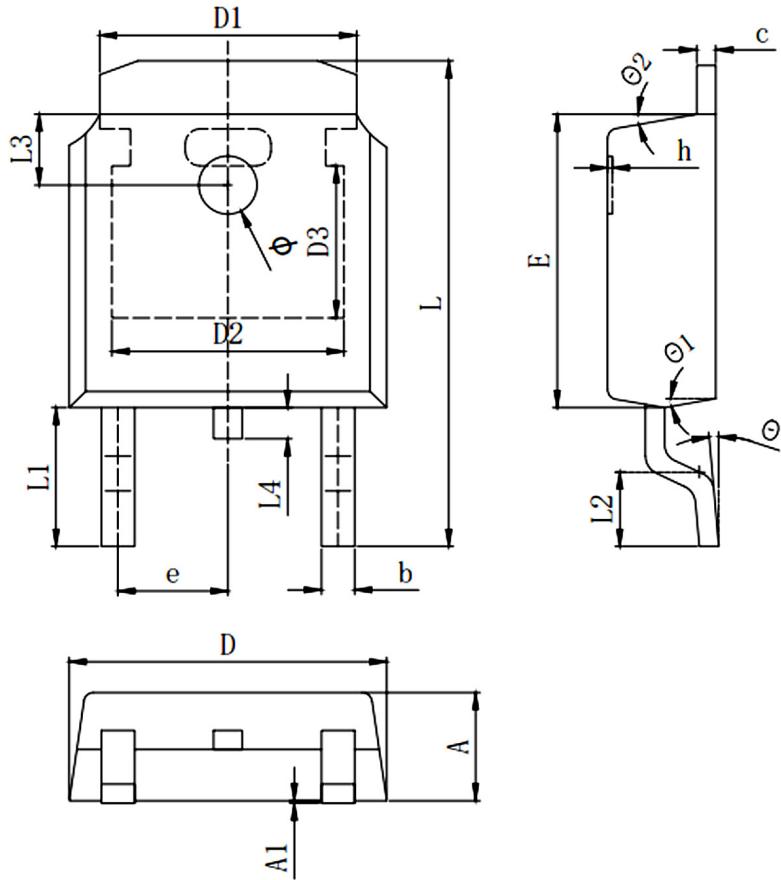


Figure 11. Normalized Maximum Transient Thermal Impedance

**TO-252 D-PAK Package**


Symbols	Millimeters		
	MIN.	Mom.	MAX.
A	2.200	2.300	2.400
A1	0.000		0.127
b	0.640	0.690	0.740
c(电镀后)	0.460	0.520	0.580
D	6.500	6.600	6.700
D1	5.334 REF		
D2	4.826 REF		
D3	3.166REF		
E	6.000	6.100	6.200
e	2.286 TYP		
h	0.000	0.100	0.200
L	9.900	10.100	10.300
L1	2.888 REF		
L2	1.400	1.550	1.700
L3	1.600 REF		
L4	0.600	0.800	1.000
Φ	1.100	1.200	1.300
θ	0°		8°
θ1	9° TYP		
θ2	9° TYP		

单击下面可查看定价，库存，交付和生命周期等信息

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